



Drawing bibliography

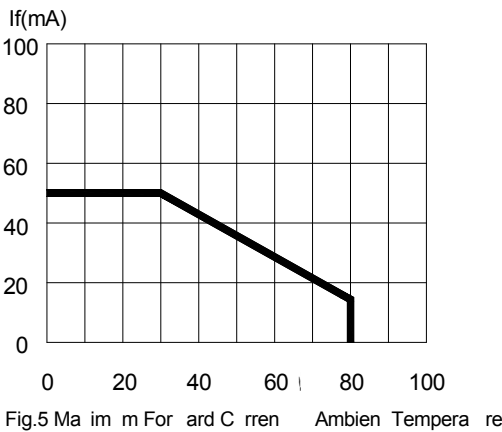
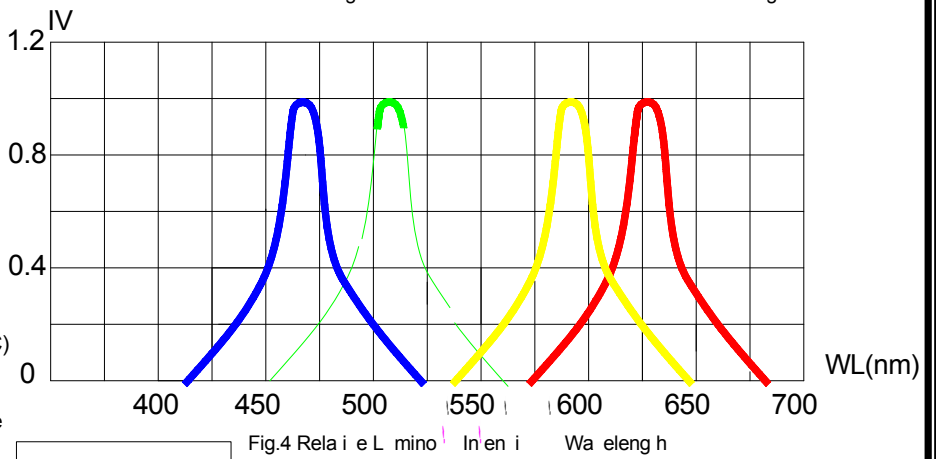
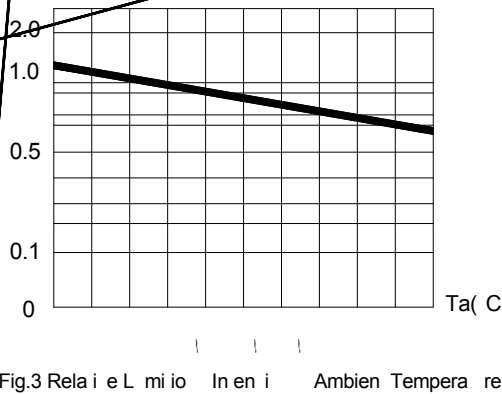
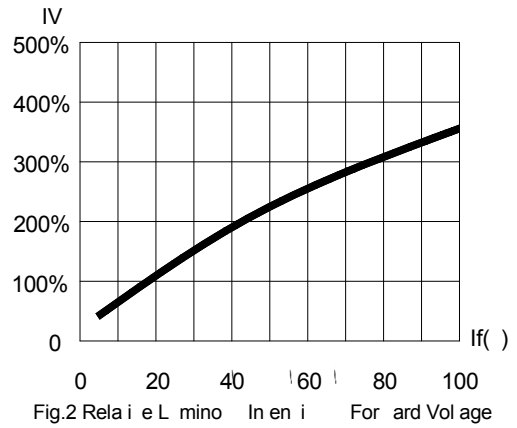
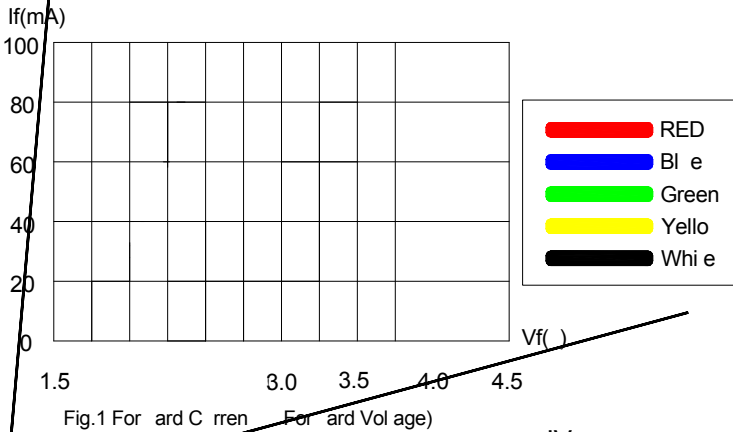
3 Characteristic

Forward current	If		30			mA
Reverse voltage	Vr		5			V
Power dissipation	Pd		110			mW
Operating temperature range	Top		-25 +80			C
Storage temperature range	Tg		-30 +80			C
Peak pulsed current 1/8 d f=1KH	Ifp		125			mA
Wavelength at peak emission	If=20mA	peak	515	520	525	nm
Spectral half bandwidth	If=20mA			10		
Forward voltage	If=20mA	Vf	3.0	3.4	3.8	V
Luminous intensity	If=20mA	I	3000	4000	5000	mcd
Viewing angle at 50% IV	If=10mA		--	120	--	Deg

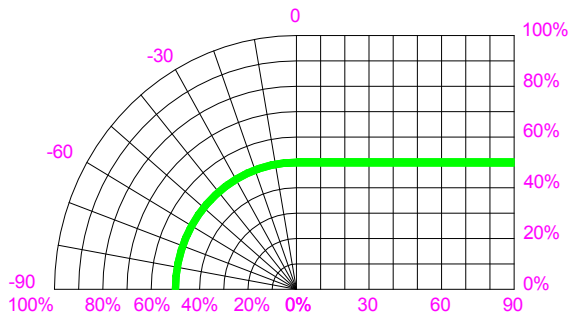


Referensi	Vr=5V	Ir	--	--	5	A
Ueflife	-	IF=20mA	100000			H

Typical Electrical/Optical Characteristic Curve
(Ta=25 Unless Otherwise Noted)



Direct Characteristic





1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temperature	High emp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heating	High emp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High storage emp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low storage emp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Temperature high emp. & high humidity	85 ± 2 / 85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position minimum 2mm from body.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from body.

- i Bracket must be bent only if 2mm from colloid.
- ii Bracket mold must be finished by fire or professional.
- iii Bracket mold must be finished before soldering.
- i Bracket mold holder should be connected between the pin, the distance gap of lead and the circuit board.

i. It should be paid attention to the ordering of all the devices in case of wrong polarity. Devices can be closed on the heat component working condition can repair the limit.

ii. It should not assemble LED when the lead are deformed.

iii. When decide on a assemble in hole, accurately account the size of hole and hole distance of the line base

i. Storage and handling

i. It should avoid any kind of quake or force on LED, before the soldering temperature return normal.

It should be careful. When clean the body with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should be handled properly, dip for no more than 3 minutes under the normal temperature.



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